

**METHOD FOR OPERATING CHEMICAL MECHANICAL  
POLISHING (“CMP”) TOOL FOR THE MANUFACTURE OF  
SEMICONDUCTOR DEVICES**

**ABSTRACT OF THE DISCLOSURE**

A method for processing integrated circuit devices including a water recycling process. The method includes operating a chemical mechanical planarization process, which includes a discharge for process water. The process water is used to process one or more semiconductor wafers. The method also selectively discharges process water from the discharge. A step of transferring the process water from the chemical mechanical planarization process to a facility process is included. The method then uses the discharged water in the facility process.

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